

**Features**

- High current operation for greater luminous output
- Low power consumption and thermal resistance
- Can be used with automatic insertion equipment
- RoHS Compliant



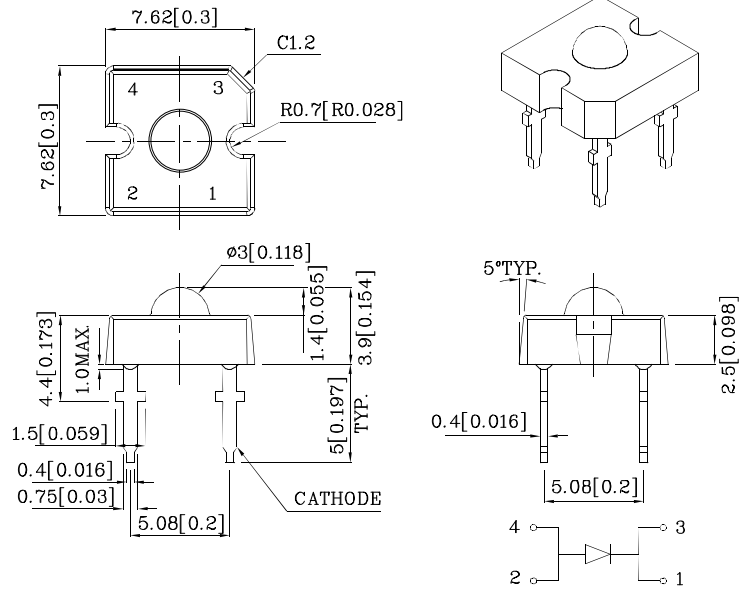
**Benefits:**

- Rugged design allows for easy maintenance
- Robust package for optimum reliability

**Typical Applications:**

- Automotive side markers
- Gaming and entertainment lighting
- Signs and road hazard indicators

**Package Schematics**



**Notes:**

1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25(0.01") unless otherwise noted.
3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T <sub>A</sub> =25°C)		M2ACY (AlGaInP)	Unit
Reverse Voltage	V <sub>R</sub>	5	V
DC Forward Current	I <sub>F</sub>	70	mA
Power Dissipation	P <sub>D</sub>	210	mW
Operating Temperature	T <sub>A</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-55 ~ +85	
Lead Solder Temperature [1.5mm Below Seating Plane.][1]	260°C For 5 Seconds		

1.No Reflow soldering .

Operating Characteristics (T <sub>A</sub> =25°C)		M2ACY (AlGaInP)	Unit
Forward Voltage (Min.) (I <sub>F</sub> =70mA)	V <sub>F</sub>	2.0	V
Forward Voltage (Typ.) (I <sub>F</sub> =70mA)	V <sub>F</sub>	2.2	V
Forward Voltage (Max.) (I <sub>F</sub> =70mA)	V <sub>F</sub>	3.0	V
Reverse Current (Max.) (V <sub>R</sub> =5V)	I <sub>R</sub>	10	uA
Wavelength of Peak Emission CIE127-2007*(Typ.) (I <sub>F</sub> =70mA)	λ <sub>P</sub>	590 590*	nm
Wavelength of Dominant Emission CIE127-2007*(Typ.) (I <sub>F</sub> =70mA)	λ <sub>D</sub>	589 590*	nm
Spectral Line Full Width At Half Maximum (Typ.) (I <sub>F</sub> =70mA)	Δλ	20	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	C	45	pF
Thermal Resistance (Typ.)	Rθj-pin	125	°C/W

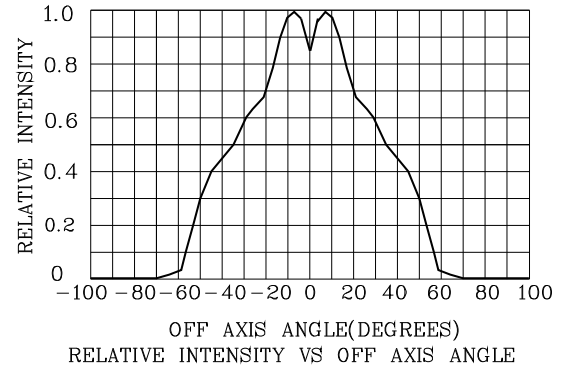
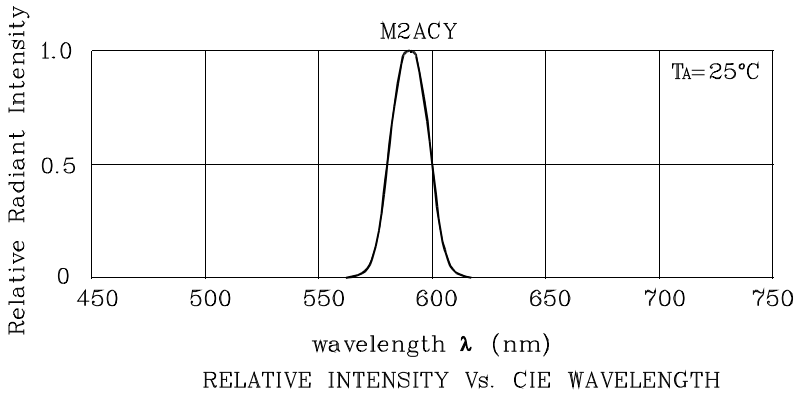
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I <sub>F</sub> =70mA) cd			Luminous Flux CIE127-2007* (I <sub>F</sub> =70mA) lm	Wavelength CIE127-2007* λP nm	Viewing Angle 2θ 1/2
				min.	typ.	typ.			
XSM2ACY983W	Yellow	AlGaInP	Water Clear	3.6*	6*	6.8*	590*	70°	

1.Luminous intensity is measured with an integrating sphere after the device has stabilized.

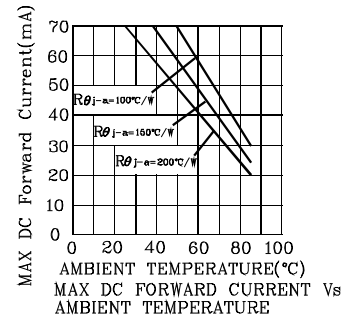
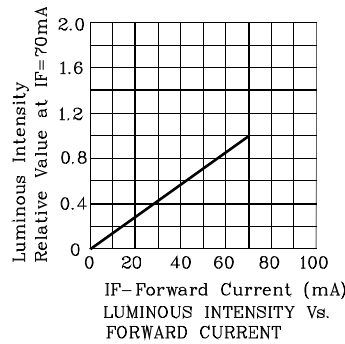
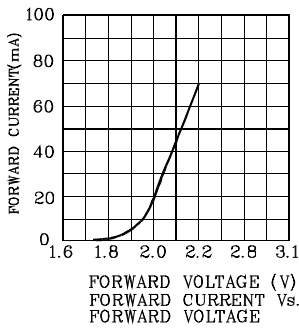
2.θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

3.LEDs are binned according to their Luminous intensity.

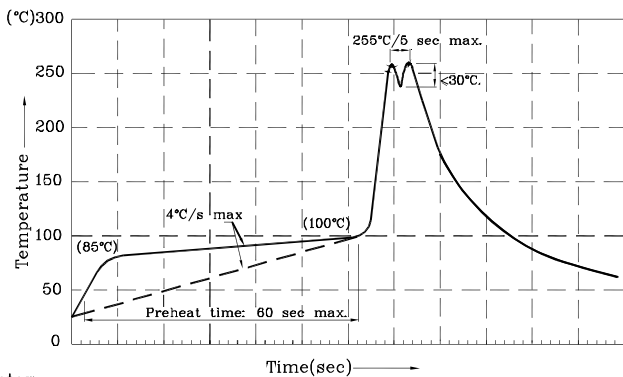
\* Luminous intensity / luminous flux value and wavelength are in accordance with CIE127-2007 standards.



❖ M2ACY



Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes:

- 1.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- 2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.
- 4.Fixtures should not incur stress on the component when mounting and during soldering process.
- 5.SAC 305 solder alloy is recommended.
- 6.No more than one wave soldering pass.

Remarks:

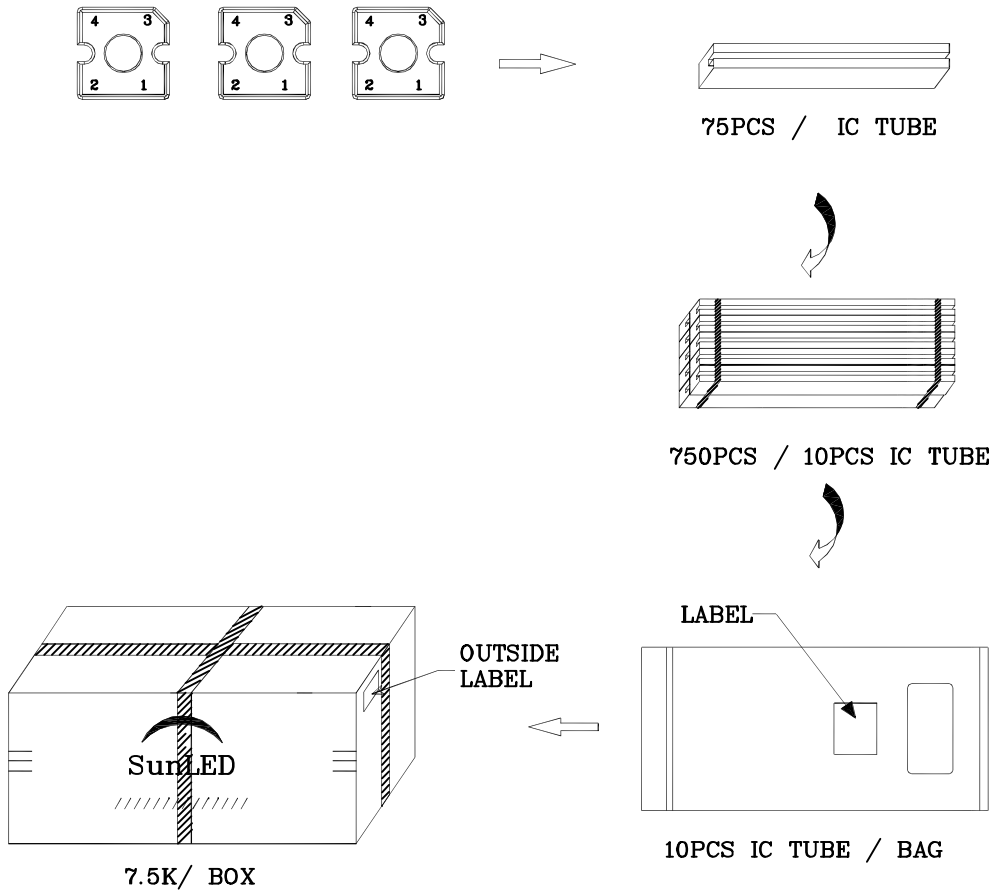
If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:


1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS






Q.C. Q.C

XX XX XXXX

PASSED

P/NO : XSxxx983x	
QTY : 750 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 XXXXXXXXXXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	